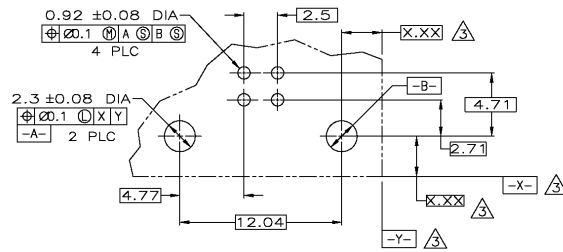
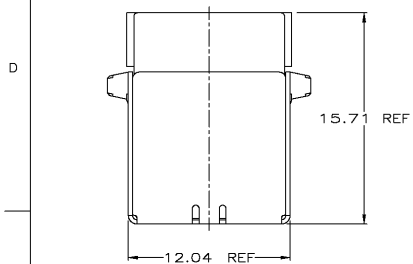
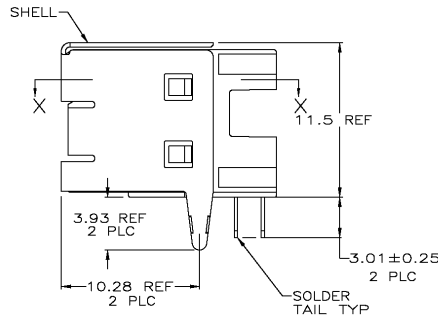
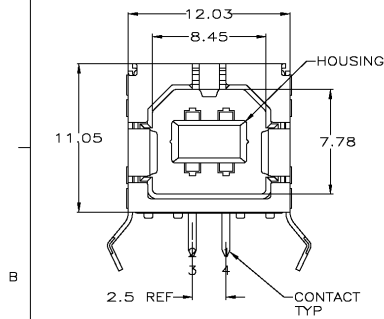


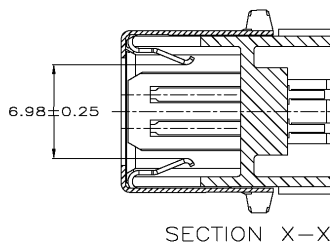
LOC	REV	DESCRIPTION	DATE	BY	APP
ES	00				
F	1	REVISED (ECR-05-014095)	11/01/05	B.W.	S.Y.



PC BOARD MOUNTING DIMENSIONS



- △ MATERIAL:
SHELL & CONTACTS: COPPER ALLOY.
HOUSING: UL 94V-0 RATED, THERMOPLASTIC, BLACK.
- △ PLATING:
CONTACTS: 0.076μm MINIMUM GOLD OVER 0.76μm MINIMUM PALLADIUM-NICKEL ON MATING AREA.
3.8μm MINIMUM MATTE TIN ON SOLDER TAILS.
BOTH OVER 1.27μm MINIMUM NICKEL.
CONTACT ALTERNATE PLATING: 0.76μm MIN GOLD ON MATING AREA, 3.8μm MIN MATTE TIN ON SOLDER TAILS, BOTH OVER 1.27μm MIN NICKEL.
SHELL: 2.0~5.0μm MINIMUM TIN.
- △ DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER.
- △ RECOMMENDED PC BOARD THICKNESS OF 1.57.
- △ PLATING:
CONTACTS: 0.76μm MINIMUM GOLD ON MATING AREA, 3.8μm MINIMUM MATTE TIN ON SOLDER TAILS, BOTH OVER 1.27μm MINIMUM NICKEL.
SHELL: 2.0~5.0μm MINIMUM TIN.
- △ PLATING:
CONTACTS: 0.38μm MINIMUM GOLD ON MATING AREA, 3.8μm MINIMUM MATTE TIN ON SOLDER TAILS, BOTH OVER 1.27μm MINIMUM NICKEL.
SHELL: 2.0~5.0μm MINIMUM TIN.
- 7 RECOMMEND:
MATING FORCE: 35N MAX.
UNMATING FORCE: 13N MIN.
RECOMMENDED MATING PLUG SHOULD MEET USB2.0 STANDARD.



△	NO	BLACK	292304-5
△	NO	BLACK	292304-4
△	YES	BLACK	292304-3
△	YES	NATURAL	292304-2
△	NO	BLACK	292304-1
PLATING	HIGH TEMPERATURE COMPATIBLE	HOUSING COLOR	PART NUMBER

DIMENSIONS: mm		DESIGNER: J. LIANG	DATE: 23FEB04	Tyco electronics corporation Shanghai, P.R.China, 200233
TOLERANCES UNLESS OTHERWISE SPECIFIED:		CHK: S. YAO	DATE: 23FEB04	
Ø	PLC	±0.1		RECEPTACLE ASSEMBLY, RIGHT ANGLE, 4 POSITION, THRU-HOLE, TYPE B UNIVERSAL SERIAL BUS, LEAD FREE VERSION SIZE: A2 CODE: 00779 DRAWING NO: C=292304 SCALE: 5:1 SHEET: 1 OF 1 REV: B
Ø	PLC	±0.1		
Ø	PLC	±0.1		
Ø	PLC	±0.1		
MATERIAL	△	△	CUSTOMER DRAWING	

292304

A

B